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MOSFET – Power, Single N-Channel 40 V, 2.8 mΩ, 110 A

NVMFS5C450NL

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C450NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted) Parameter Symbol Value Unit v Drain-to-Source Voltage VDSS 40 V Gate-to-Source Voltage ±20 V_{GS} Continuous Drain 110 A T_C = 25°C I_D Current R_{0JC} $T_{\rm C} = 100^{\circ}{\rm C}$ 81 (Notes 1, 3) Steady State $T_C = 25^{\circ}C$ Power Dissipation P_D 68 W $R_{\theta,IC}$ (Note 1) $T_{C} = 100^{\circ}C$ 34 $T_A = 25^{\circ}C$ Continuous Drain 27 А I_D Current R_{0JA} 19 (Notes 1, 2, 3) $T_{A} = 100^{\circ}C$ Steady State Power Dissipation w $T_A = 25^{\circ}C$ P_D 3.7 R_{0JA} (Notes 1 & 2) $T_A = 100^{\circ}C$ 1.6 **Pulsed Drain Current** $T_A = 25^{\circ}C, t_p = 10 \ \mu s$ 740 A IDM °C Operating Junction and Storage Temperature T_J, T_{stg} -55 to + 175Source Current (Body Diode) 76 А Is Single Pulse Drain-to-Source Avalanche E_{AS} 215 mJ Energy $(I_{L(pk)} = 7 A)$ °C Lead Temperature for Soldering Purposes T_{L} 260 (1/8" from case for 10 s)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

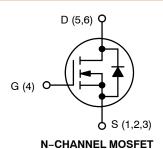
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	2.2	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	41	

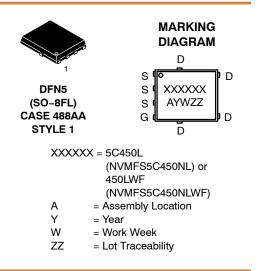
1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	2.8 mΩ @ 10 V	110 A
40 V	4.4 mΩ @ 4.5 V	IIUA





ORDERING INFORMATION

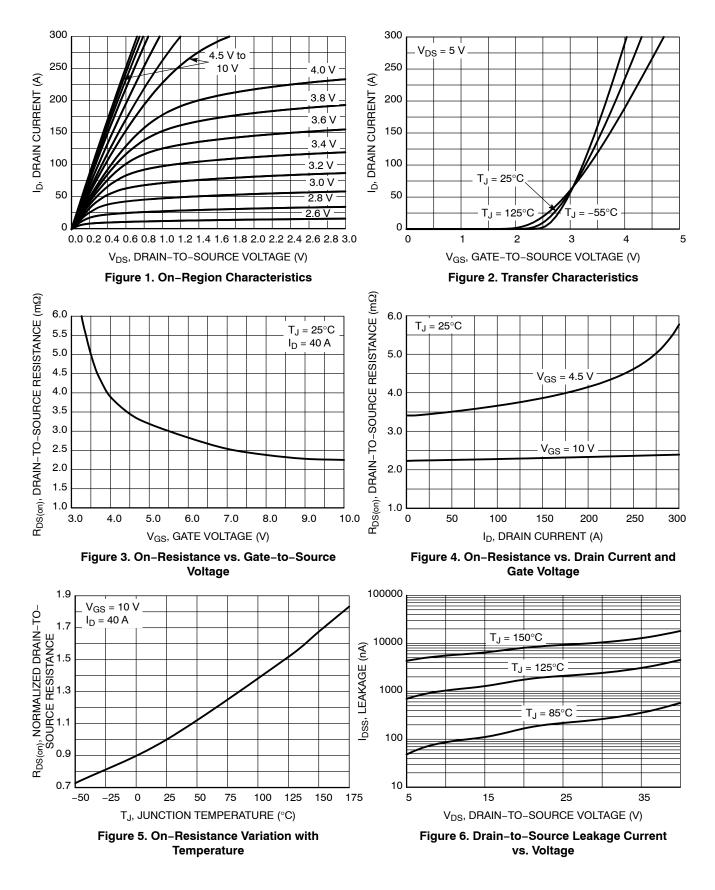
See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = $25^{\circ}C$ unless otherwise specified)

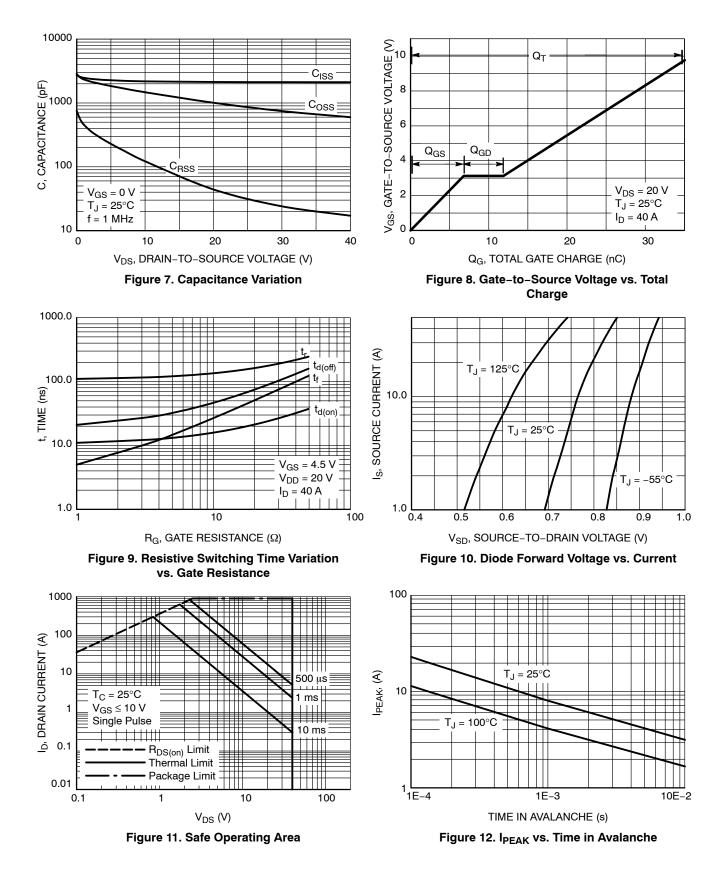
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS					•		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D	= 250 μA	40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				1.6		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$			10	10 250 μΑ
		V _{DS} = 40 V	T _J = 125°C			250	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _C	_{iS} = 20 V			100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{I}$	_D = 60 μA	1.2		2.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.3		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 4.5 V	I _D = 40 A		3.5	4.4	mΩ
		V _{GS} = 10 V	I _D = 40 A		2.3	2.8	1
Forward Transconductance	9 _{FS}	V _{DS} =15 V, I _D = 40 A			120		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE						
Input Capacitance	C _{ISS}				2100		
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}, V_{DS} = 20 \text{ V}$ $V_{GS} = 4.5 \text{ V}, V_{DS} = 20 \text{ V}; \text{ I}_{D} = 40 \text{ A}$			1000		pF
Reverse Transfer Capacitance	C _{RSS}				42		
Total Gate Charge	Q _{G(TOT)}				16		nC
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 40 A			35		nC
Threshold Gate Charge	Q _{G(TH)}				4		1
Gate-to-Source Charge	Q _{GS}	V _{GS} = 4.5 V, V _{DS} = 20 V; I _D = 40 A			7		nC V
Gate-to-Drain Charge	Q _{GD}				5		
Plateau Voltage	V _{GP}				3.2		
SWITCHING CHARACTERISTICS (Note 5	5)				<u> </u>		
Turn-On Delay Time	t _{d(ON)}				11		
Rise Time	t _r	$V_{cc} = 45 V V$	no = 20 V		110		1
Turn-Off Delay Time	t _{d(OFF)}	$\begin{array}{l} V_{GS} = 4.5 \; V, \; V_{DS} = 20 \; V, \\ I_{D} = 40 \; A, \; R_{G} = 1 \; \Omega \end{array}$			21		ns
Fall Time	t _f				5		
DRAIN-SOURCE DIODE CHARACTERIS	TICS						
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V,$ $I_{S} = 40 A$	T _J = 25°C		0.84	1.2	
			T _J = 125°C		0.72		V
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _s /dt = 100 A/µs, I _S = 40 A			41		
Charge Time	ta				19		ns
Discharge Time	t _b				22		
Reverse Recovery Charge	Q _{RR}				31		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



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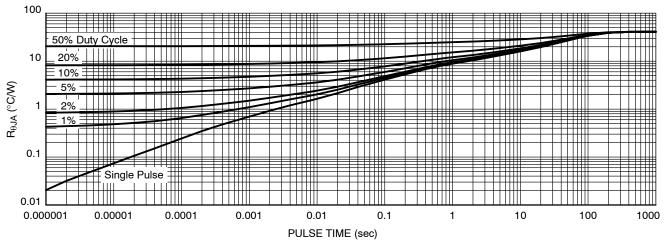


Figure 13. Thermal Characteristics

Device	Marking	Package	Shipping [†]
NVMFS5C450NLT1G	5C450L	DFN5 (Pb–Free)	1500 / Tape & Reel
NVMFS5C450NLWFT1G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C450NLT3G	5C450L	DFN5 (Pb–Free)	5000 / Tape & Reel
NVMFS5C450NLWFT3G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	5000 / Tape & Reel
NVMFS5C450NLAFT1G	5C450L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5C450NLWFAFT1G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel
NVMFS5C450NLWFET1G	450LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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